



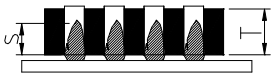
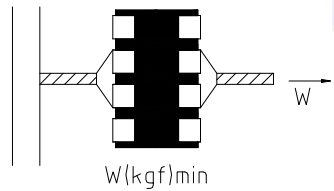
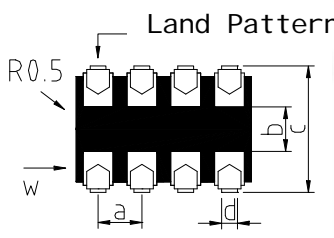
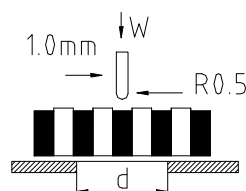
KING CORE ELECTRONICS INC.

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RELIABILITY TEST – BA4□ SERIES

ITEM	SPECIFICATION	TEST CONDITION										
Operation temp. Range	-25°C ~ +85°C	~										
Storage temp. & Humidity range	40°C max., 70% RH max.	At packing condition										
Resistance to solder heat	1 No damage such as cracks should be caused in chip element. 2 More than 75% of the terminal electrode shall be covered with new solder. 3 Impedance change: ± within 30%	Preheat Temperature: 100 to 150°C Preheat time: 1 min. Solder : Sn/Ag/Cu Temperature : 260 ± 10°C Dipping time: 10 ± 0.5 sec										
Solderability	1 More than 90% of the terminal electrode shall be covered with new solder. 2 Impedance change: ± within 30%	Preheat Temperature: 100 to 150°C Preheat time: 1 min. Solder : Sn/Ag/Cu Temperature : 245 ± 5°C Dipping time: 4 ± 1 sec										
Reflow soldering	1 More than 50% of the terminal electrode shall be covered with new solder. $S \geq 1/3T$ 	Preheat Temperature: 150°C Preheat time: 1 min. Solder : Sn/Ag/Cu Temperature : 250°C Soldering time: 10sec. max. (Reflow soldering profile)										
Tensile strength (terminal strength)	1 The terminal electrode shall be break off not the ferrite damage. $W = 1.2 \text{kgf min}$											
Adhesion of terminal electrode (flexure strength)	1 No mechanical damage. <table border="1" data-bbox="462 1523 630 1702"> <tr><td>A</td><td>0.8</td></tr> <tr><td>B</td><td>0.8</td></tr> <tr><td>C</td><td>3.0</td></tr> <tr><td>D</td><td>0.4</td></tr> <tr><td>W</td><td>5.0</td></tr> </table> Unit: mm (a, b, c, d), kef (w)	A	0.8	B	0.8	C	3.0	D	0.4	W	5.0	Land Pattern 
A	0.8											
B	0.8											
C	3.0											
D	0.4											
W	5.0											
Body strength (bending strength)	1 The body shall not be damaged by forces applied on the right. Unit: mm (d), kef (w) <table border="1" data-bbox="462 1870 630 1948"> <tr><td>D</td><td>2.0</td></tr> <tr><td>W</td><td>5(3)</td></tr> </table>	D	2.0	W	5(3)							
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W002.A00



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ITEM	SPECIFICATION	TEST CONDITION
Drop	1 No mechanical damage. 2 Impedance change: \pm within30%	Drop 10 times a concrete floor from a height of 91cm
Thermal shock (Temperature cycle)	1 No mechanical damage. 2 Impedance change: \pm within30%	Step1. $-40^{\circ}\text{C} \pm 3^{\circ}\text{C}$, 30 \pm 3min. Step2. $+85^{\circ}\text{C} \pm 3^{\circ}\text{C}$, 30 \pm 3min. Number of cycle: 100 times
Heat load resistance	1 No mechanical damage. 2 Impedance change: \pm within30%	Temperature: $85 \pm 2^{\circ}\text{C}$ Applied current: rated current Times: 1,000 hours Measured at room ambient Temperature after placing for 24 hours.
Low temperature resistance	1 No mechanical damage. 2 Impedance change: \pm within30%	Temperature : $-40 \pm 5^{\circ}\text{C}$ Times: 1,000 hours Measured at room ambient Temperature after placing for 24 hours.
Humidity resistance	1 No mechanical damage. 2 Impedance change: \pm within30%	Temperature : $-40 \pm 2^{\circ}\text{C}$ Humidity: 90~95% RH Measured at room ambient Temperature after placing for 24 hours.
Humidity load resistance	1 No mechanical damage. 2 Impedance change: \pm within30%	Temperature: $40 \pm 2^{\circ}\text{C}$ Humidity: 90~95% RH Applied current: rated current Times: 500 hours Measured at room ambient Temperature after placing for 24 hours.

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